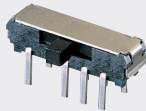


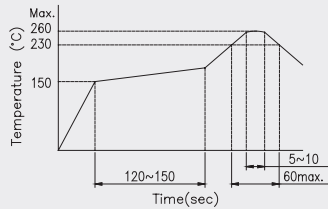
NSS509 Series

■ Features

- DIP type.
- Tall height.



Rating	DC12V 0.1A
Stroke	2.0 ± 0.3 mm
Contact Resistance	70mΩ max.
Insulation Resistance	DC500V -100MΩ min
Withstand Voltage	AC500V - 1 minute
Recommended Reflow Soldering Profile	



Number of Reflow Pass : 2 cycles

Recommended Wave Soldering Profile

Parameters	Lead-Free Specification
Preheating Time	60 sec max.
Preheating Temperature	100°C max.
Continuous Dipping Time	3~5 sec max.
Soldering Temperature	260°C max.

Recommended Manual Soldering Profile

	Temperature	Time
Manual Soldering Temperature	350 °C (max.)	3 Sec.(max.)

The solder iron and solder shall be applied at a distance of 1.91 mm to 2.54 mm from the plastic housing.

Durability	10,000 cycles
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■ DIP - D Type Horizontal 2 Poles 3 Positions

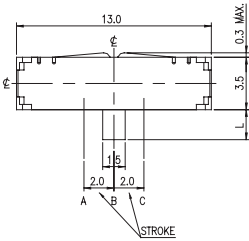
13.0L x 3.5W x 3.5H

Product No.	L	Package
NSS509-223N-CCCD1B	2.0	Bulk
NSS509-223N-CCDD1B	3.2	

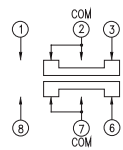
■ Specifications

Timing	Non-Shorting
Operating Force	A→B, C→B : 200±150gf B→A, B→C : 250±150gf

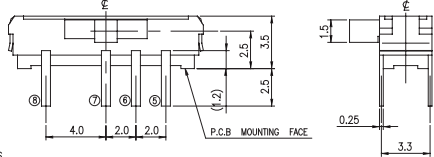
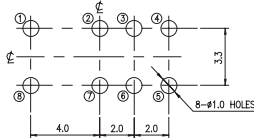
■ Outline Drawing



Schematic



P.C.B Layout



General Tolerance : ±0.2mm.